G2R50MT33-CAL
3300 V 50 mΩ SiC MOSFET

GeneSiC SEMICONDUCTOR

Silicon Carbide MOSFET

N-Channel Enhancement Mode

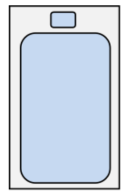
For physical chip dimensions please contact engineering@diedevices.com

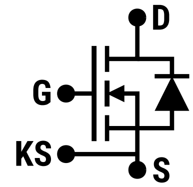
V_{DS}	=	3300 V
$R_{DS(ON)(Typ.)}$	=	50 mΩ
$I_{D (T_C = 100°C)}$	=	49 A

Features

- Softer $R_{DS(ON)}$ v/s Temperature Dependency
- LoRing™ - Electromagnetically Optimized Design
- Smaller $R_{G(INT)}$ and Lower Q_G
- Low Device Capacitances (C_{OSS}, C_{RSS})
- Superior Cost-Performance Index
- Robust Body Diode with Low V_F and Low Q_{RR}
- Normally Off-Stable Temperature up to 175°C
- Industry-Leading UIL & Short-Circuit Robustness

Bare Chip





D = Drain
G = Gate
S = Source
KS = Kelvin Source

RoHS

REACH

Advantages

- Compatible with Commercial Gate Drivers
- Low Conduction Losses at all Temperatures
- Reduced Ringing
- Faster and More Efficient Switching
- Lesser Switching Spikes and Lower Losses
- Better Power Density and System Efficiency
- Ease of Paralleling without Thermal Runaway
- Higher System Reliability

Applications

- Traction
- Solar String Inverters
- EV- Fast Chargers
- Pulsed Power
- Switched Mode Power Supply
- Energy Storage
- Solid State Transformers
- Solid State Circuit Breakers

Absolute Maximum Ratings (At T_C = 25°C Unless Otherwise Stated)

Parameter	Symbol	Conditions	Values	Unit	Note
Drain-Source Voltage	$V_{DS(max)}$	V_{GS} = 0 V, I_D = 100 µA	3300	V	
Gate-Source Voltage (Dynamic)	$V_{GS(max)}$		-10 / +25	V	
Gate-Source Voltage (Static)	$V_{GS(op)}$	Recommended Operation	-5 / +20	V	
Continuous Forward Current	I_D	T_C = 25°C, V_{GS} = -5 / +20 V	69	A	
		T_C = 100°C, V_{GS} = -5 / +20 V	49		
		T_C = 135°C, V_{GS} = -5 / +20 V	36		
Pulsed Drain Current	$I_{D(pulse)}$	t_P ≤ 3µs, D ≤ 1%, V_{GS} = 20 V, Note 1	235	A	
Power Dissipation	P_D	T_C = 25°C	647	W	Note 2
Non-Repetitive Avalanche Energy	E_{AS}	L = 11.2 mH, I_{AS} = 20.0 A	2250	mJ	
Operating and Storage Temperature	T_j , T_{stg}		-55 to 175	°C	

Note 1: Pulse Width t_P Limited by $T_{j(max)}$

Electrical Characteristics (At T_C = 25°C Unless Otherwise Stated)

Parameter	Symbol	Conditions	Values Min.	Values Typ.	Values Max.	Unit	Note
Drain-Source Breakdown Voltage	V_{DSS}	V_{GS} = 0 V, I_D = 100 µA	3300			V	
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 3300 V, V_{GS} = 0 V		1		µA	
Gate Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = 25 V V_{DS} = 0 V, V_{GS} = -10 V			100 -100	nA	
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 10.0 mA V_{DS} = V_{GS}, I_D = 10.0 mA, T_j = 175°C	2.5	3.50 2.40		V	Fig. 9
Transconductance	g_{fs}	V_{DS} = 10 V, I_D = 40 A V_{DS} = 10 V, I_D = 40 A, T_j = 175°C		15.3 16.4		S	Fig. 4
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS} = 20 V, I_D = 40 A V_{GS} = 20 V, I_D = 40 A, T_j = 175°C		50 105	65	mΩ	Fig. 5-8
Input Capacitance	C_{iss}	V_{DS} = 1000 V, V_{GS} = 0 V f = 1 MHz, V_{AC} = 25mV		7301		pF	Fig. 11
Output Capacitance	C_{oss}			130		pF	Fig. 11
Reverse Transfer Capacitance	C_{rss}			12.3		pF	Fig. 11
C_{oss} Stored Energy	E_{oss}			84		µJ	Fig. 12
C_{oss} Stored Charge	Q_{oss}			254		nC	
Effective Output Capacitance (Energy Related)	$C_{o(er)}$			168		pF	Note 3
Effective Output Capacitance (Time Related)	$C_{o(tr)}$			254		pF	Note 3
Gate-Source Charge	Q_{gs}	V_{DS} = 1000 V, V_{GS} = -5 / +20 V I_D = 40 A Per IEC607478-4		120		nC	Fig. 10
Gate-Drain Charge	Q_{gd}			100		nC	Fig. 10
Total Gate Charge	Q_g			340		nC	Fig. 10
Internal Gate Resistance	$R_{G(int)}$	f = 1 MHz, V_{AC} = 25 mV		1.2		Ω	
Turn-On Switching Energy (Body Diode)	E_{On}	T_j = 25°C; V_{GS} = -5/+20V; $R_{G(ext)}$ = 3 Ω, I_D = 50 A; V_{DD} = 1700 V		687		µJ	Fig. 18
Turn-Off Switching Energy (Body Diode)	E_{Off}			304		µJ	Fig. 18
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 1700 V, V_{GS} = -5/+20V $R_{G(ext)}$ = 3 Ω, I_D = 50 A Timing relative to V_{DS}, Resistive load		42		ns	Fig. 20
Rise Time	t_r			36		ns	Fig. 20
Turn-Off Delay Time	$t_{d(off)}$			35		ns	Fig. 20
Fall Time	t_f			30		ns	Fig. 20

**The chip technology was characterized up to 200 V/ns. The measured dV/dt was limited by measurement test setup and package.*

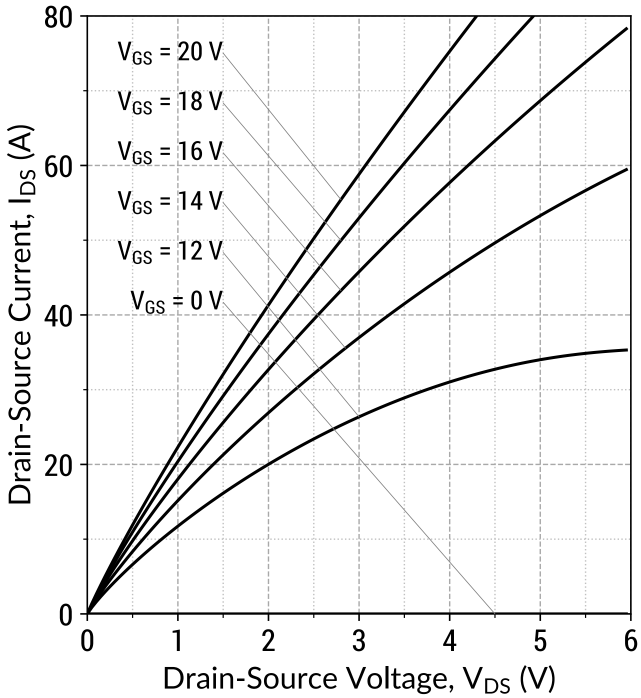
Note 2: Assuming $Rth_{JC(max)}$ = 0.23°C/W

Note 3: $C_{o(er)}$, a lumped capacitance that gives same stored energy as C_{OSS} while V_{DS} is rising from 0 to 1000V.
$C_{o(tr)}$, a lumped capacitance that gives same charging times as C_{OSS} while V_{DS} is rising from 0 to 1000V.

Reverse Diode Characteristics

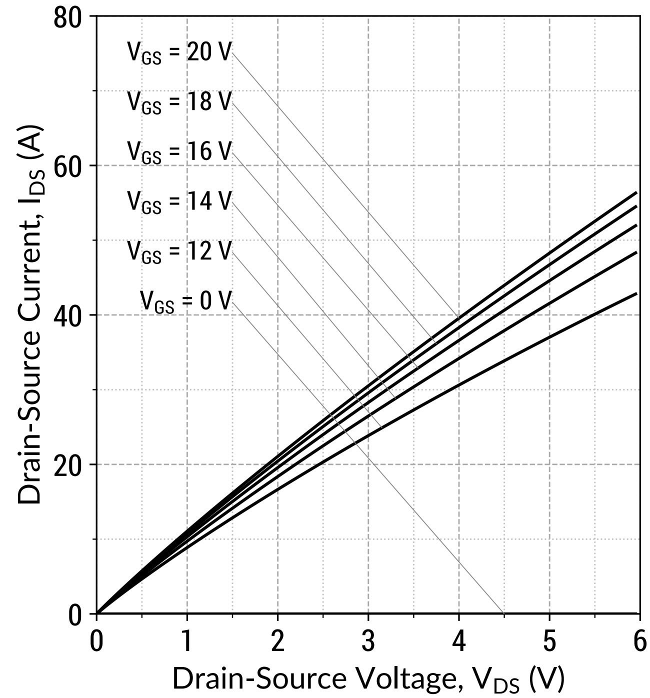
Parameter	Symbol	Conditions	Values Min.	Values Typ.	Values Max.	Unit	Note
Diode Forward Voltage	V_{SD}	V_{GS} = -5 V, I_{SD} = 20 A V_{GS} = -5 V, I_{SD} = 20 A, T_j = 175°C		4.1 3.5		V	Fig. 13-14
Continuous Diode Forward Current	I_S	V_{GS} = -5 V, T_c = 100°C	56			A	
Diode Pulse Current	$I_{S(pulse)}$	V_{GS} = -5 V, Note 1		224		A	
Reverse Recovery Time	t_{rr}	V_{GS} = -5 V, I_{SD} = 50 A, V_R = 1700 V dif/dt = 500 A/µs, T_j = 25°C		154		ns	
Reverse Recovery Charge	Q_{rr}			740		nC	
Peak Reverse Recovery Current	I_{rrm}			17		A	
Reverse Recovery Time	t_{rr}	V_{GS} = -5 V, I_{SD} = 50 A, V_R = 1700 V dif/dt = 500 A/µs, T_j = 175°C		204		ns	
Reverse Recovery Charge	Q_{rr}			2840		nC	
Peak Reverse Recovery Current	I_{rrm}			38		A	

Figure 1: Output Characteristics (T_j = 25°C)



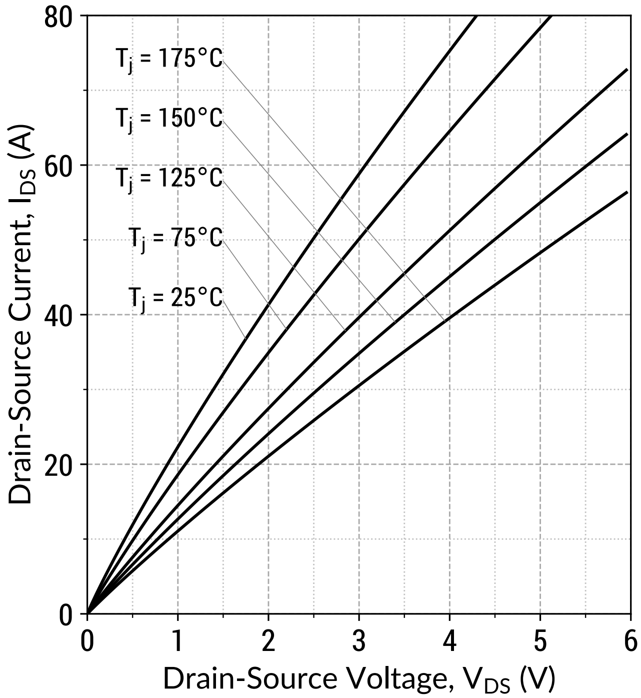
$I_D = f(V_{DS}, V_{GS})$; t_P = 250 µs

Figure 2: Output Characteristics (T_j = 175°C)



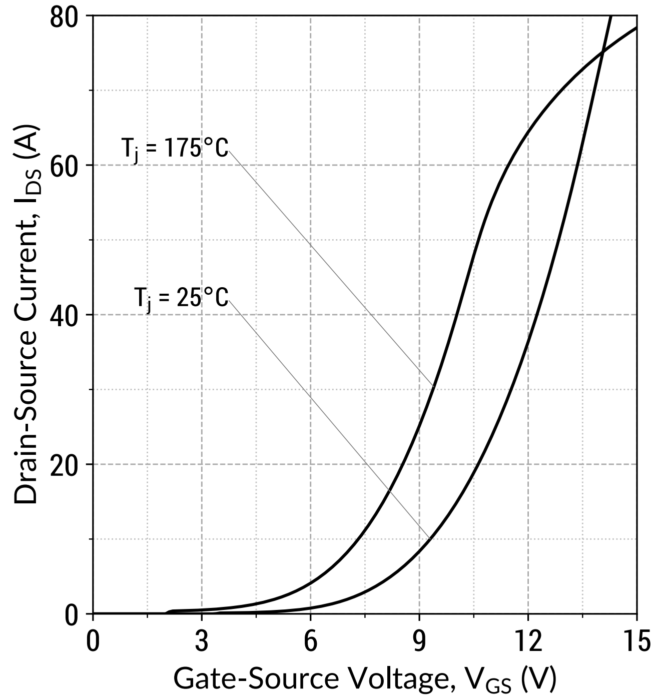
$I_D = f(V_{DS}, V_{GS})$; t_P = 250 µs

Figure 3: Output Characteristics (V_{GS} = 20 V)



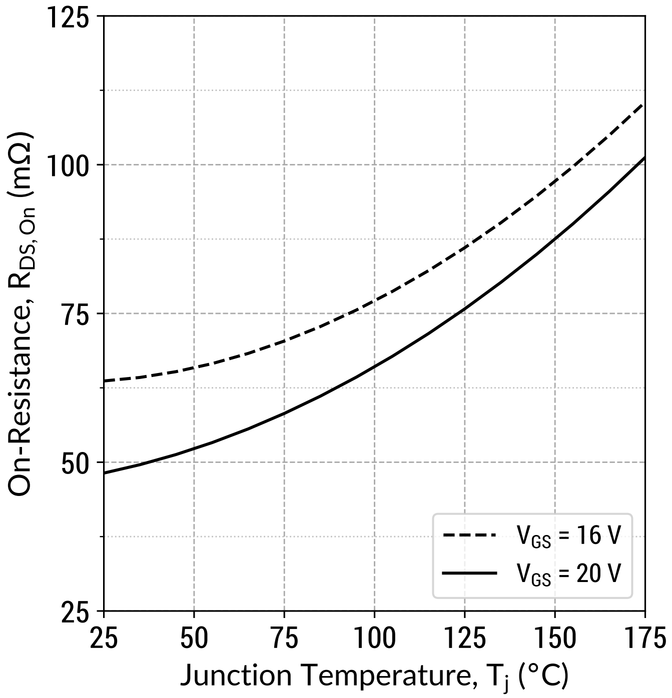
$I_D = f(V_{DS}, T_j)$; t_P = 250 µs

Figure 4: Transfer Characteristics (V_{DS} = 10 V)



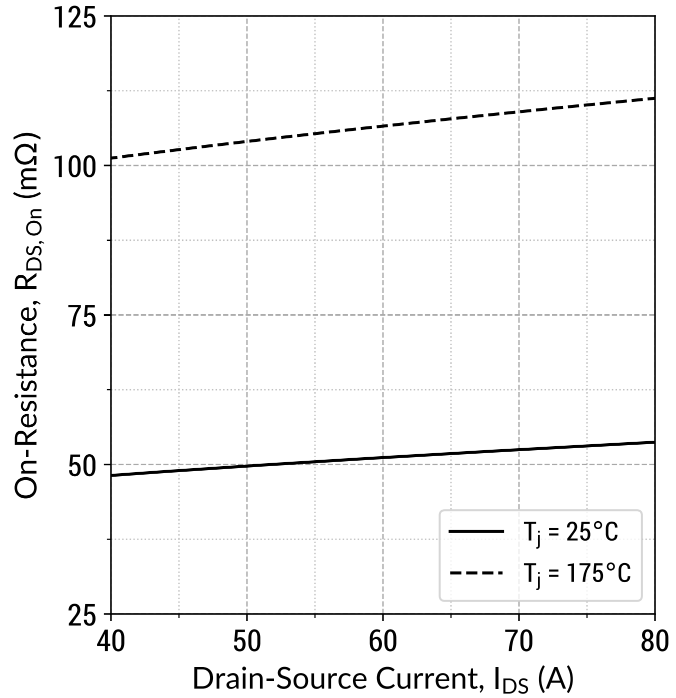
$I_D = f(V_{GS}, T_j)$; t_P = 100 µs

Figure 5: On-State Resistance v/s Temperature



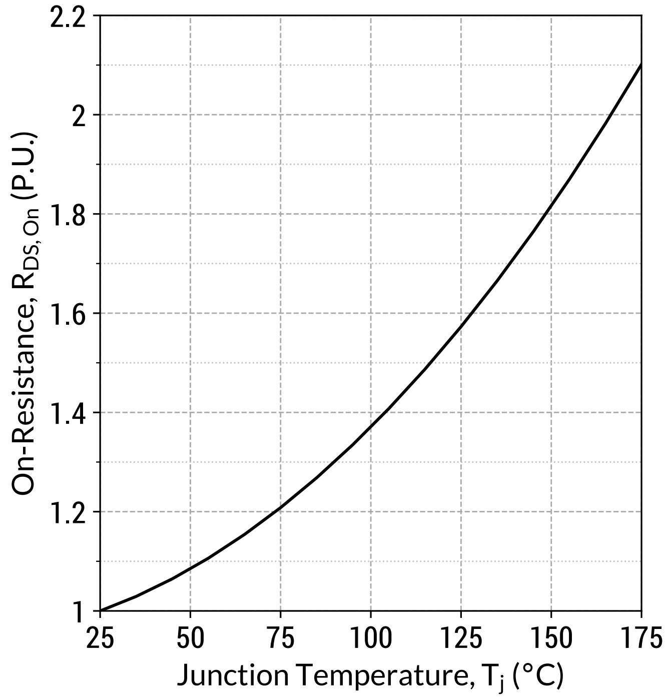
$R_{DS(ON)} = f(T_j, V_{GS})$; t_P = 250 µs; I_D = 40 A

Figure 6: On-State Resistance v/s Drain Current



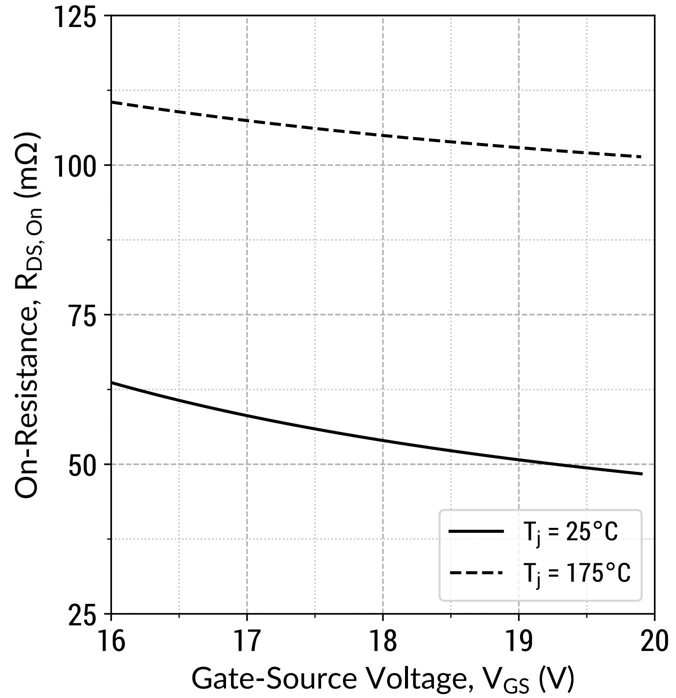
$R_{DS(ON)} = f(T_j, I_D)$; t_P = 250 µs; V_{GS} = 20 V

Figure 7: Normalized On-State Resistance v/s Temperature



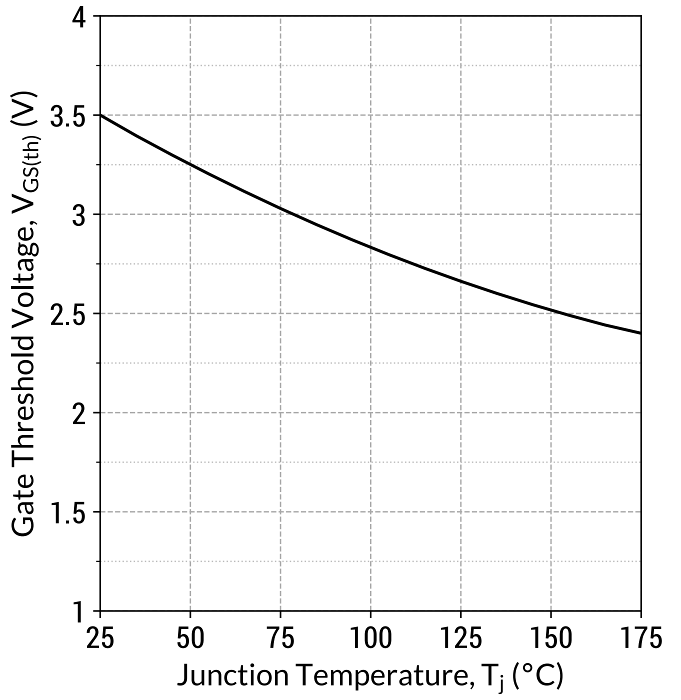
$R_{DS(ON)} = f(T_j)$; t_P = 250 µs; I_D = 40 A; V_{GS} = 20 V

Figure 8: On-State Resistance v/s Gate Voltage



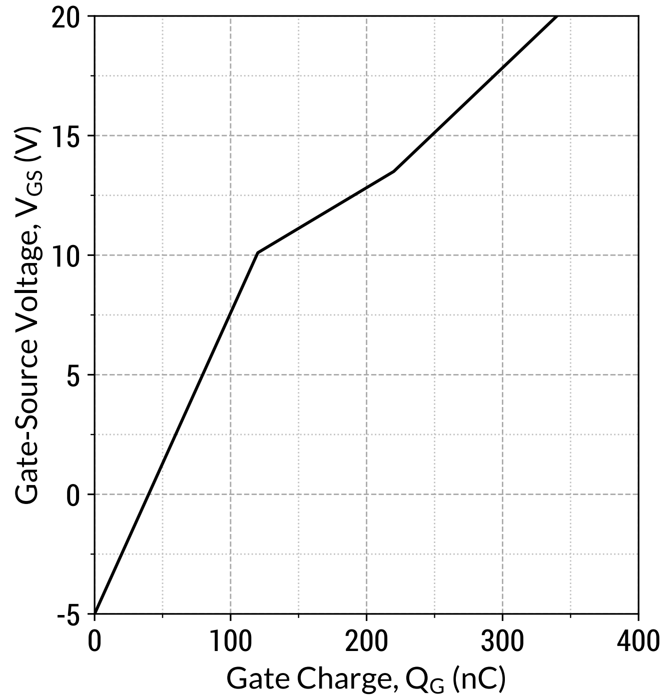
$R_{DS(ON)} = f(T_j, V_{GS})$; t_P = 250 µs; I_D = 40 A

Figure 9: Threshold Voltage Characteristics



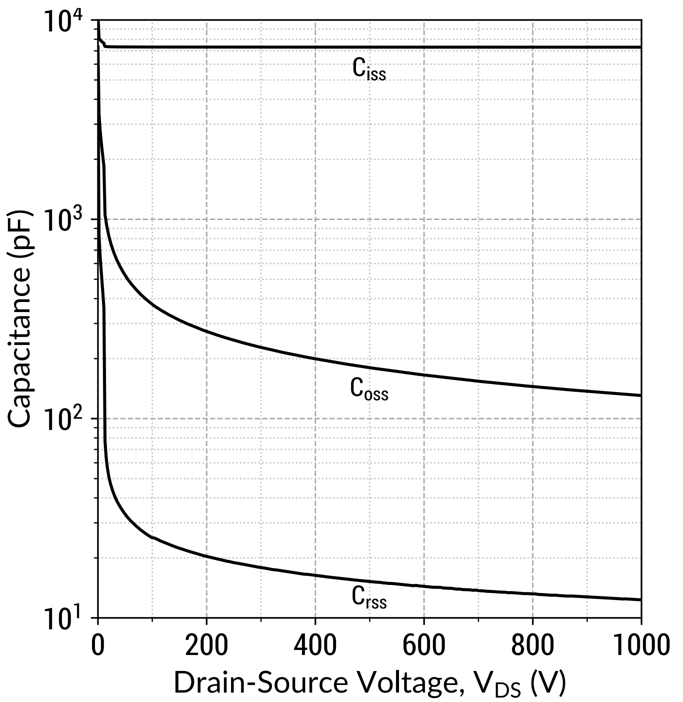
$V_{GS(th)} = f(T_j)$; $V_{DS} = V_{GS}$; $I_D = 10.0$ mA

Figure 10: Gate Charge Characteristics



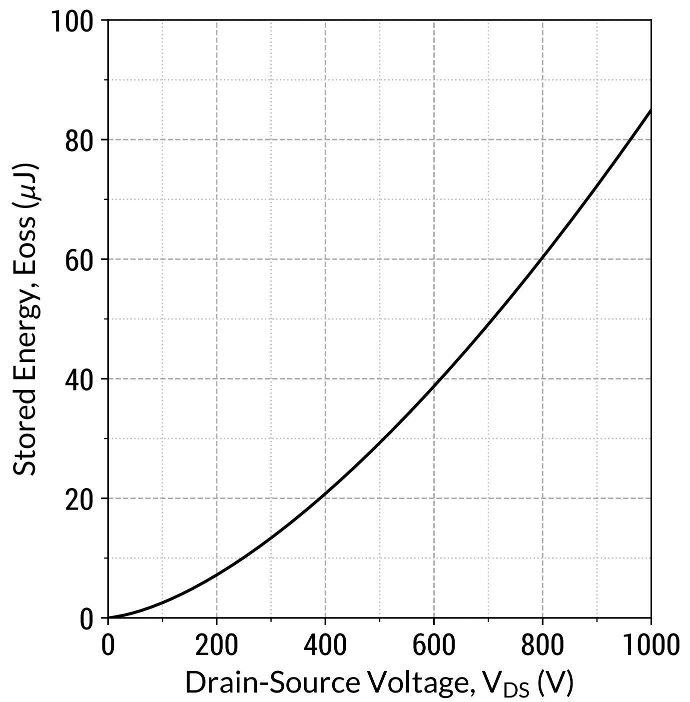
$I_D = 40$ A; $V_{DS} = 1000$ V; $T_c = 25$°C

Figure 11: Capacitance v/s Drain-Source Voltage



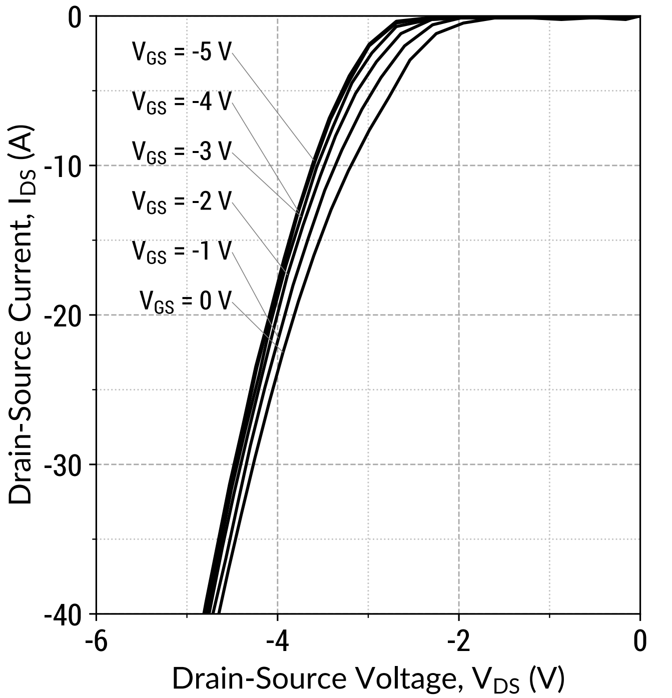
f = 1 MHz; V_{AC} = 25mV

Figure 12: Output Capacitor Stored Energy



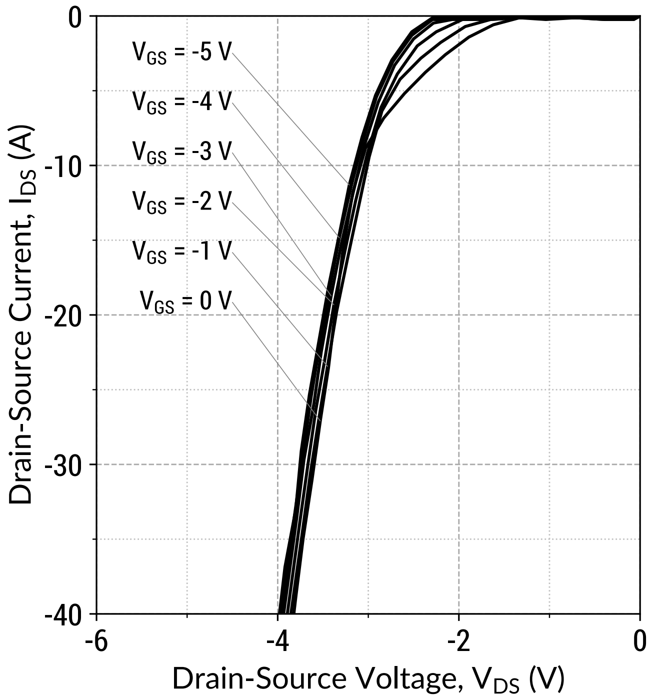
$E_{oss} = f(V_{DS})$

Figure 13: Body Diode Characteristics (T_j = 25°C)



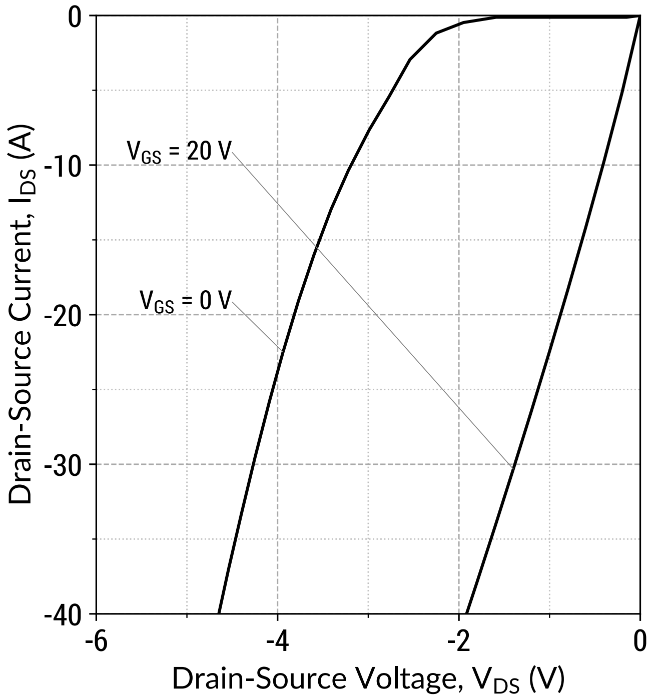
$I_D = f(V_{DS}, V_{GS})$; t_P = 250 µs

Figure 14: Body Diode Characteristics (T_j = 175°C)



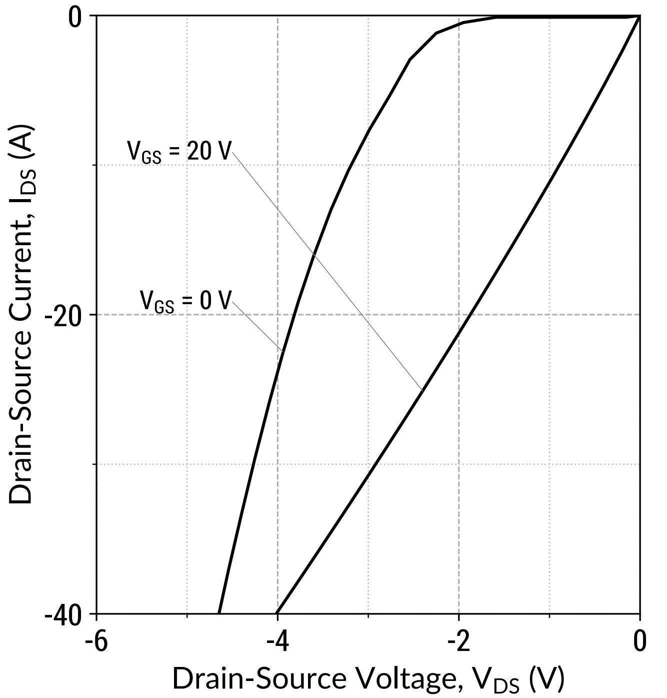
$I_D = f(V_{DS}, V_{GS})$; t_P = 250 µs

Figure 15: Third Quadrant Characteristics (T_j = 25°C)



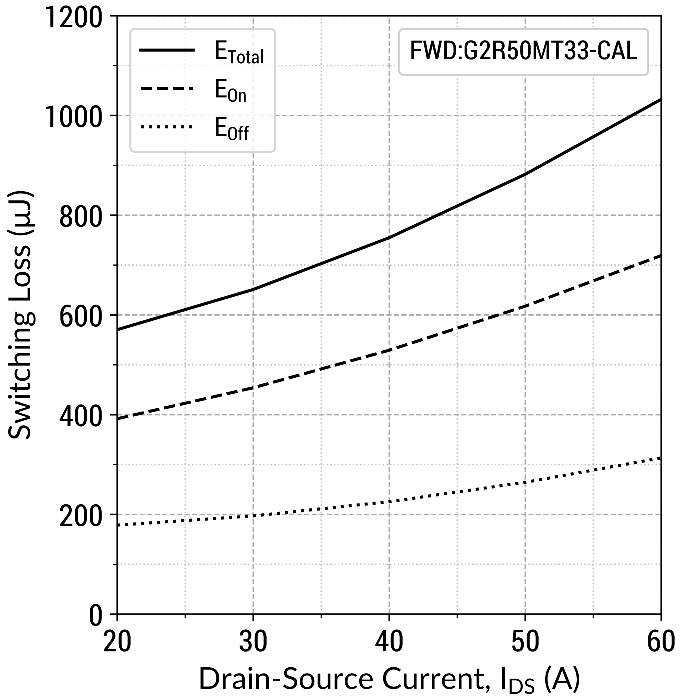
$I_D = f(V_{DS}, V_{GS})$; t_P = 250 µs

Figure 16: Third Quadrant Characteristics (T_j = 175°C)



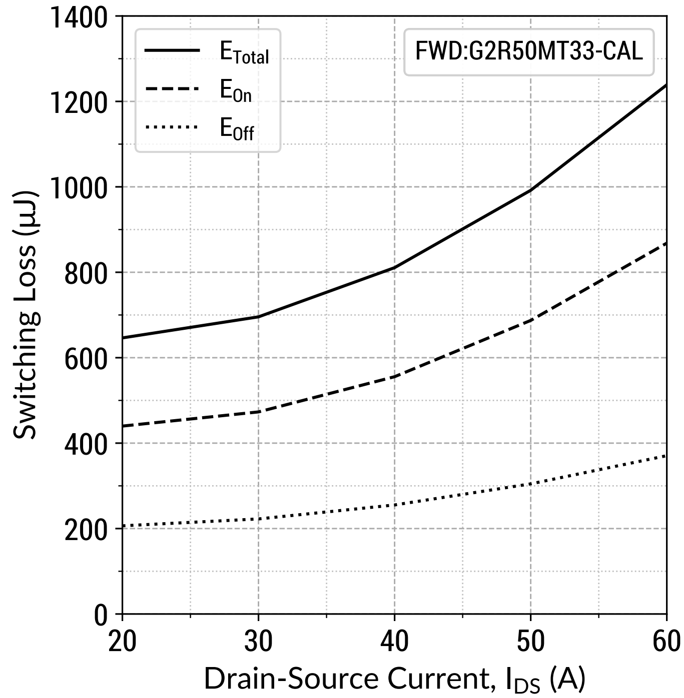
$I_D = f(V_{DS}, V_{GS})$; t_P = 250 µs

Figure 17: Resistive Switching Energy v/s Drain Current (V_{DD} = 1500V)



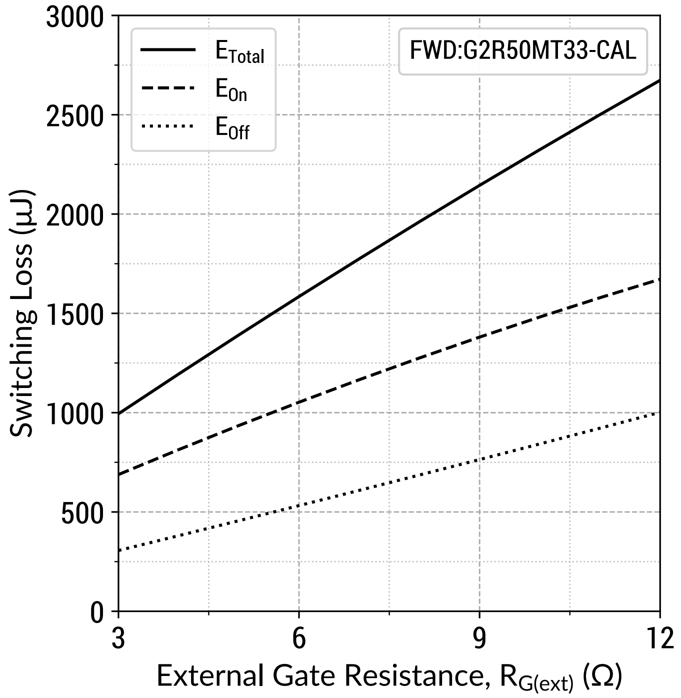
T_j = 25°C; V_{GS} = -5/+20V; $R_{G(ext)}$ = 3 Ω

Figure 18: Resistive Switching Energy v/s Drain Current (V_{DD} = 1700V)



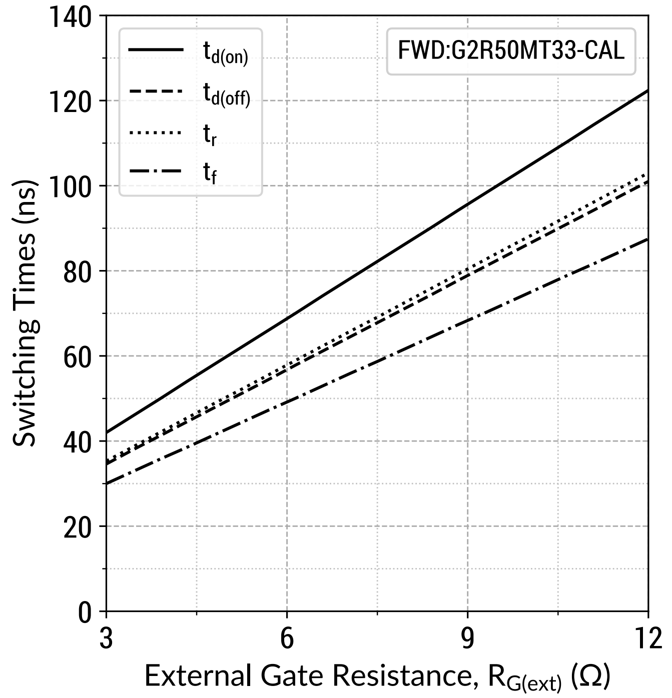
T_j = 25°C; V_{GS} = -5/+20V; $R_{G(ext)}$ = 3 Ω

Figure 19: Resistive Switching Energy v/s $R_{G(ext)}$ (V_{DD} = 1700V)



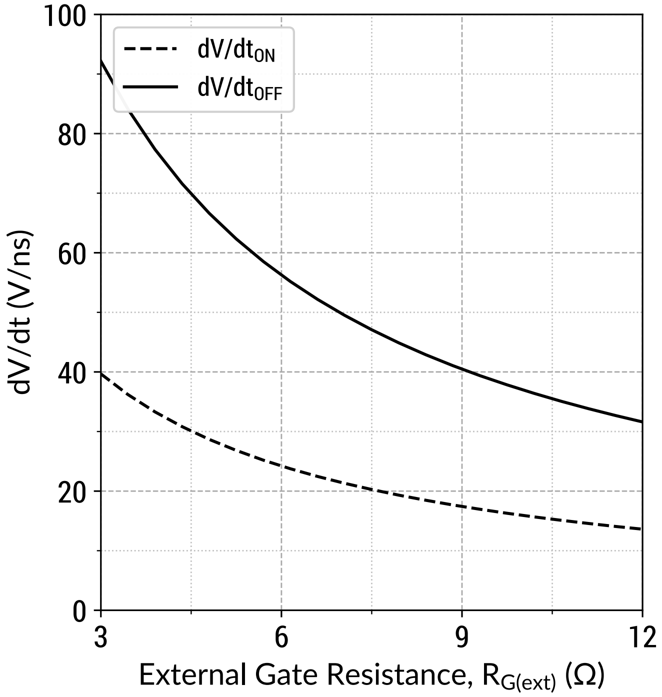
T_j = 25°C; V_{GS} = -5/+20V; I_{DS} = 50 A

Figure 20: Switching Time v/s $R_{G(ext)}$ (V_{DD} = 1700V)



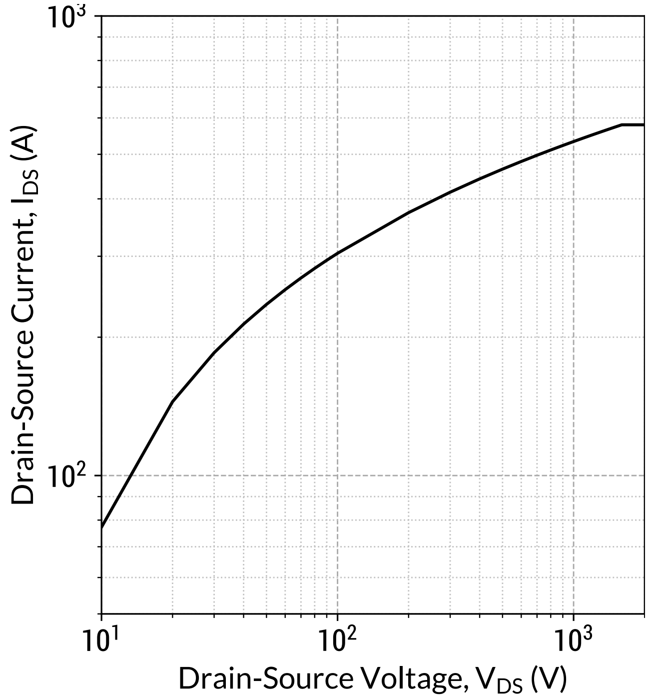
T_j = 25°C; V_{GS} = -5/+20V; I_{DS} = 50 A

Figure 21: dV/dt v/s $R_{G(ext)}$ (V_{DD} = 1700V)



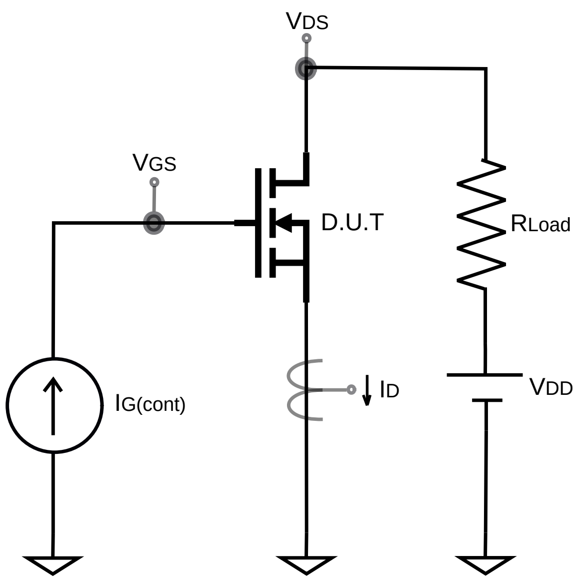
T_j = 25°C; V_{GS} = -5/+20V; I_{DS} = 50 A

Figure 22: High Current IV

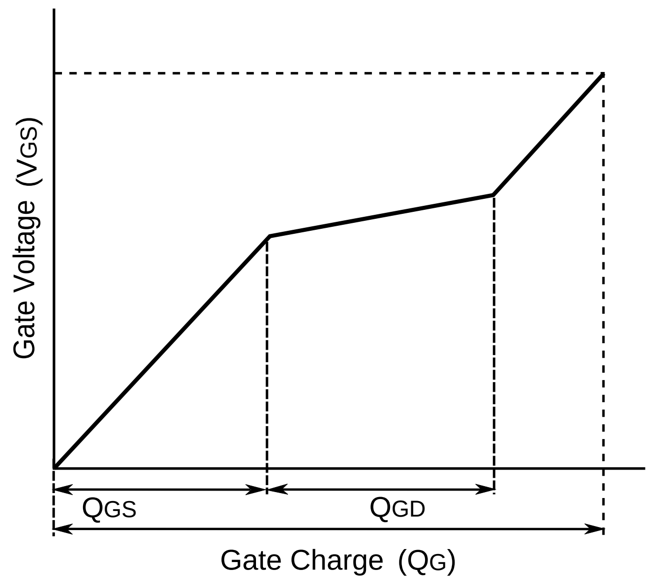


$I_D = f(V_{DS})$; $t_P \leq 3$ μs; V_{GS} = 20 V

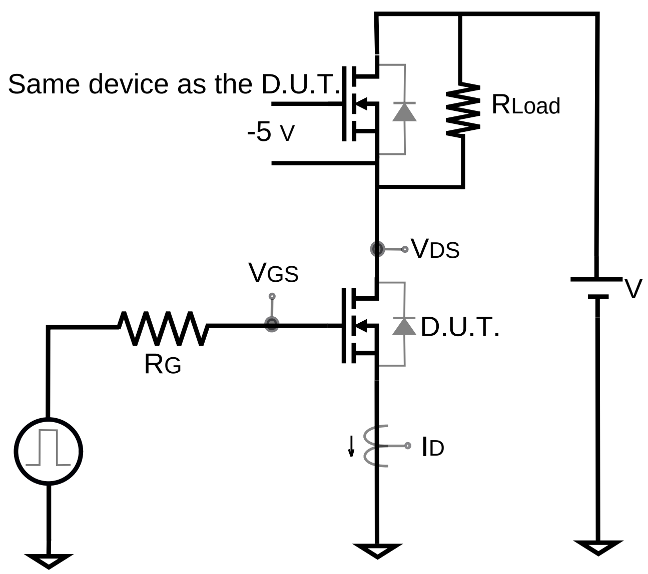
Gate Charge Circuit



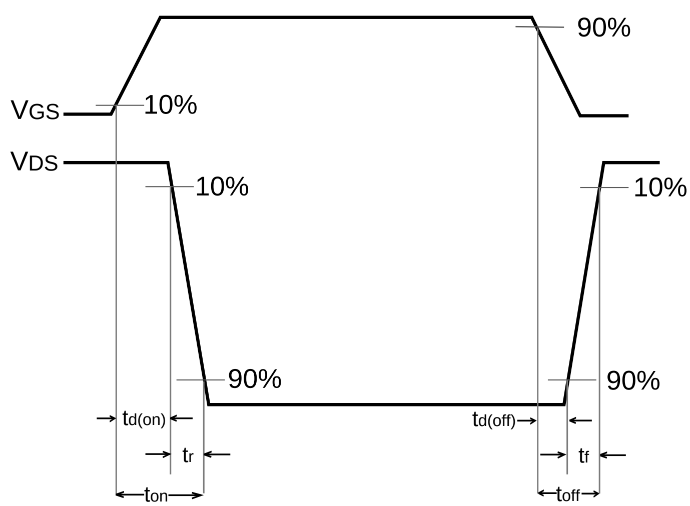
Gate Charge Waveform



Switching Time Circuit



Switching Time Waveform



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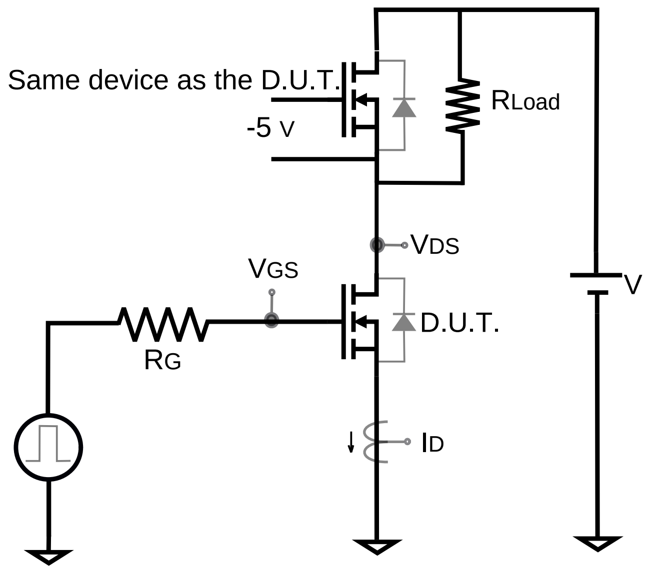
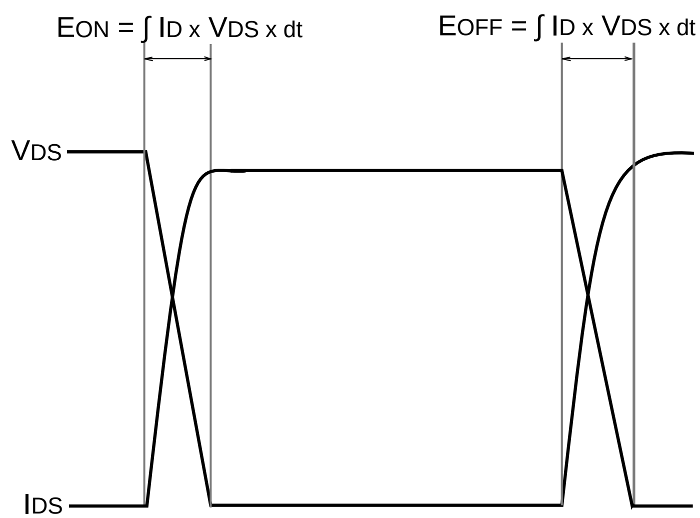
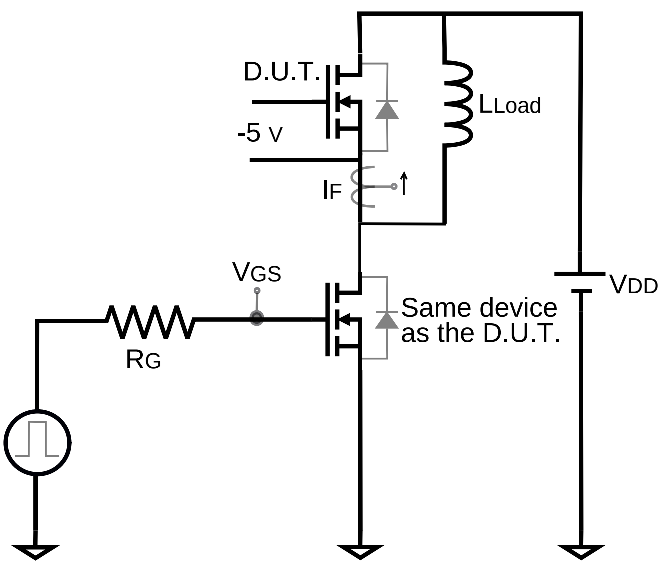
Switching Energy Circuit



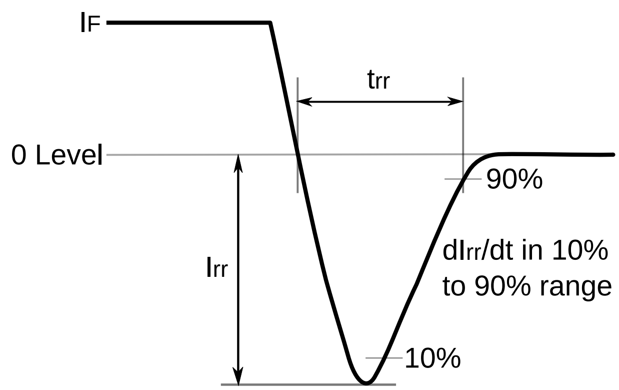
Switching Energy Waveform



Reverse Recovery Circuit



Reverse Recovery Waveform



Mechanical Parameters

This information is confidential, please contact **sales@genesicsemi.com** to learn more.

Chip Dimensions

This information is confidential, please contact **sales@genesicsemi.com** to learn more.

NOTE

1. CONTROLLED DIMENSION IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS.

Compliance

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS 2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863. RoHS Declarations for this product can be obtained from your GeneSiC representative.

REACH Compliance

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a GeneSiC representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

Disclaimer

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Related Links

- SPICE Models: https://www.genesicsemi.com/sic-mosfet/G2R50MT33-CAL/G2R50MT33-CAL_SPICE.zip
- PLECS Models: https://www.genesicsemi.com/sic-mosfet/G2R50MT33-CAL/G2R50MT33-CAL_PLECS.zip
- CAD Models: https://www.genesicsemi.com/sic-mosfet/G2R50MT33-CAL/G2R50MT33-CAL_3D.zip
- Gate Driver Reference: https://www.genesicsemi.com/technical-support
- Evaluation Boards: https://www.genesicsemi.com/technical-support
- Reliability: https://www.genesicsemi.com/reliability
- Compliance: https://www.genesicsemi.com/compliance
- Quality Manual: https://www.genesicsemi.com/quality

Revision History

- Rev 21/Jun: Updated switching time and switching energy data
- Supersedes: Rev 20/Jun, Rev 20/Sep, Rev 20/Dec, Rev 21/Feb

www.genesicsemi.com/sic-mosfet/

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